

Claims for Patent application #10/803,626 rewritten/re-ordered such that they identify a single embodiment of the invention: A robust modular electronic device without direct electrical connection or control. This is in response to a Restriction Requirement regarding this patent application. Inventor: Robert J. Rapp Customer #41400, [rappj@sbglobal.net](mailto:rappj@sbglobal.net), 408-247-3304, 1120 Ranchero Way #10 San Jose, Ca 95117; Patent examiner Truc T. Nguyen (Art Unit 2833). *RJR 7-12-05*

**Claims:**

**Claim 1:**

A modular electronic device where non direct electrical contact (non-contact) mechanisms are used for inter-module communication, and where modules are attached forming an extendable structure with extendable function.

**Claim 2:**

A device as in Claim 1 where non-direct electrical contact control mechanisms are used.

**Claim 3:**

A device as in Claim 2 where alignment mechanisms and retention mechanisms are used to align and attach modules.

**Claim 4:**

A device as in Claim 3 where the modules are sealed, with electronics inside.

**Claim 5:**

A device as in Claim 4 where inter-module power is distributed using magnetic induction/transformer action.

**Claim 6:**

A device as in Claim 5 where an alignment mechanism is used as a transformer core.

**Claim 7:**

A device as in Claim 6 where modules are liquid filled for cooling electronics contained within.

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**Claim 8:**

A device as in Claim 6 where modules are liquid filled for withstanding a high pressure environment.

**Claim 9:**

A device as in Claim 4 where inter-module power is distributed using a non-contact power distribution mechanism.

**Claim 10:**

A device as in Claim 9 where alignment mechanisms are used to improve the efficiency of non-contact power distribution mechanisms.

**Claim 11:**

A device as in Claim 4 where alignment mechanisms are used to improve the efficiency of non-contact inter-module communication mechanisms.

**Claim 12:**

A system and method for extending the function of an electronic device where a plurality of modules as described in preceding claims are aligned and attached as the structure of the electronic device is extended.